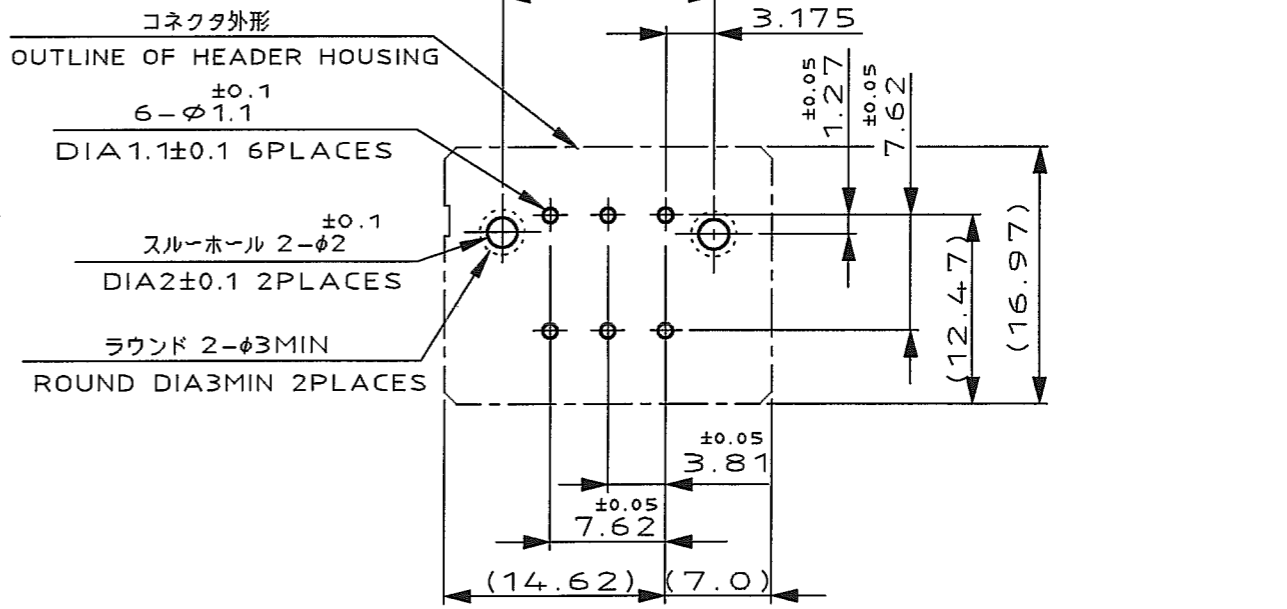
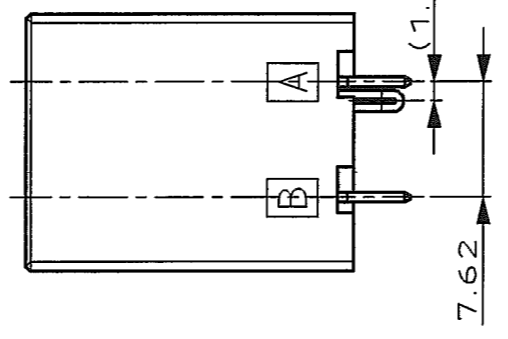
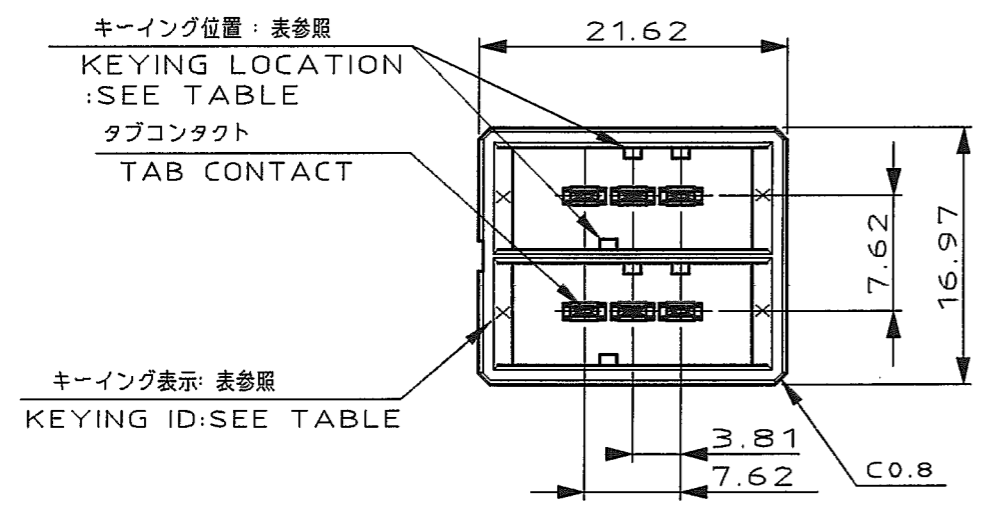
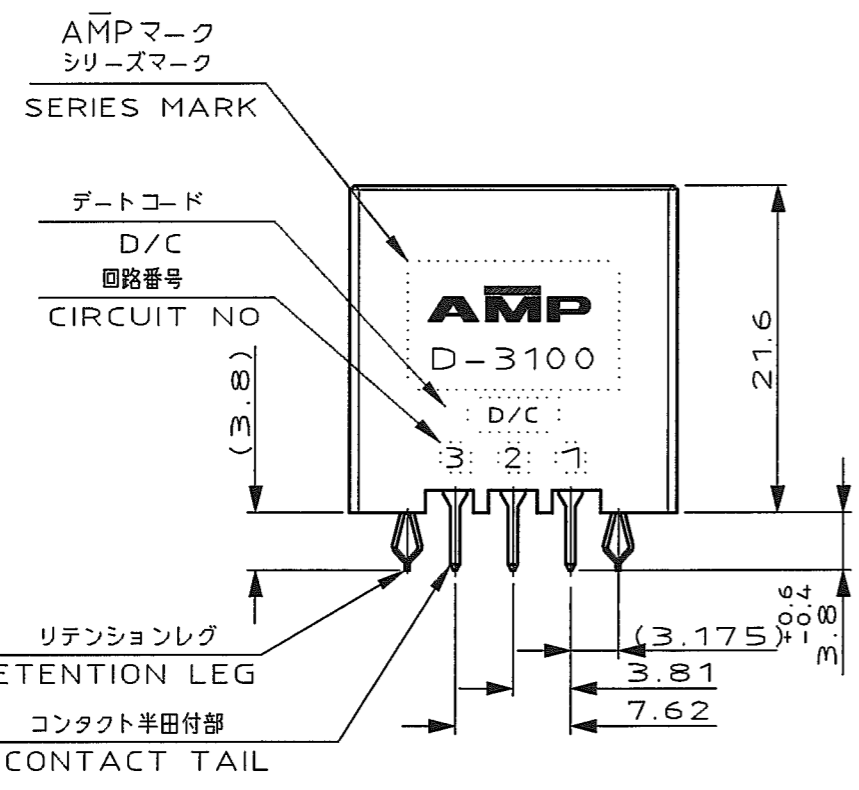


NUMBER 178141
 METRIC
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT
 PRINT DIST



推奨基板取付け穴寸法
 PC 基板厚: 1.6±0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6±0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
- △6 FINISH (CONTACT AREA): 0.38μm MIN GOLD PLATING OVER NI PLATING
- △3 FINISH (CONTACT AREA): 0.76μm MIN GOLD PLATING OVER NI PLATING
- △4 FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- △5 FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- △6 FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒
 コンタクト: 銅合金
 リテンションレグ: 銅合金
- △6 めっき: コンタクト: 全面Ni下地
 接触部: 0.38μm MIN金めっき
- △3 めっき: コンタクト: 全面Ni下地
 接触部: 0.76μm MIN金めっき
- △4 めっき: コンタクト: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
- △5 めっき: リテンションレグとコンタクト半田付部
 : ニッケル下地の上に半田めっき
- △6 めっき: リテンションレグとコンタクト半田付部
 : ニッケル下地の上にスズめっき

A ROW		X	Y	△6	△4	3-178141-5
B ROW				△6	△3	3-178141-3
A ROW		X	X	△6	△4	1-178141-5
B ROW				△6	△3	1-178141-3
				△6	△2	1-178141-2
KEYING LOCATION				A ROW KEYING	B ROW KEYING	FINISH
				製品番号	PART NO.	



WIRE RANGE	INSULATION DIA	NAME			
mm²(AWG -)	mmφ	DYNAMIC D-3100 3.81X7.62PITCH(V) 6 POS.HDR CONN.ASS'Y			
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照	一般公差 (GENERAL TOLERANCE)	SIZE	LOC	NUMBER
DR. 19 APR 94 N. Matsubara	DE. 19 APR 94 N. Matsubara	100% ±0.3 100% 300% ±0.4 300% 100% ±0.45 角度: ±3'	A3	J	178141
E1 REVISED PER ECO-11-005030	RK HMR 28MAR 11	CHK. 20 APR 94 S. MANABE	APP. 20 APR 94 S. MANABE	SCALE	REV. SHEET
LTR REVISION RECORD	DR CHK DATE	2-1	E1	1 OF 1	